## STEREO CONFIGURATION CHANGE REQUEST

		TITLE:				CLASS:			NUMB	ER:				
For <b>C</b>	Office							Ι						
Use	Only							II	DATE:					
CONFIGURED ITEM:						ORIGINATOR: PRIORITY:								
					Name: Branislav Kecman									
STS Number: Payload: STEREO						Organization: Caltech $\checkmark$ Re					Rou	tine		
Component :				Experiment: IMPACT/SEP Phone: 62			626-	0-395-4264 Urgent						
Component Part #: Serial #:						Email: kecman@srl.caltech.edu					Emergency			
TYPE OF REQUEST:				RESPONSIBLE										
				ORGANIZATION/INDIVIDUAL:				(If yes attach additional pages)						
Configuration								COST		v	es		No	
	Deviation #						COSI		I	es	V	NO		
√ Waiver #			#					SCHEDULE:				.1	NI -	
	Other:							SCHE	DULE:	Y	es	$\checkmark$	No	
REA	SONS FC				_				RETEST	-	JIREI	):		
	Improver			yload Failure New Document:				No						
DDO	Reliabilit	<u> </u>		ation Requirements Iditional pages as required):	C	Other:			Ye	s				
Instead of using known-good-die in the PHASIC hybrid we plan to use unknown-good-die that were not subject to 100% electrical test prior to installation in the hybrid. This violates the hybrid element evaluation requirements for Class H (see document affected below). The need for a waiver has been identified in the PHASIC Hybrid PDR Action Item 24. <b>RATIONALE</b> (Attach additional pages as required): Mixed-signal ASIC die used in the PHASIC hybrid is noise-sensitive and can be fully tested only in a hybrid circuit environment because of the optimum conditions offered by the hybrid package. Testing such a die at the wafer level gives limited diagnostics (i.e., DC measurements), it cannot accomplish the AC test requirements, and is impractical in this case. Our plan is to test the die in the hybrid and accept the loss of those hybrids where both the first- and the second-installed die prove to be defective. Class H allows die to be replaced only once. The experience with PHASIC hybrids so far has been that even imperfect die can be considered for flight applications where not all of its 32 pulse-height analysis channels are required to be fully functional.														
	time as		a tins ap	proach successfully o	II AU	CE project a	na we	ere co	maen	t that	11 WI	11 W	OLK	
DOC	CUMENT	S/DRA	WINGS AF	FECTED (Document No./	Title	/Section) :								
Doc	. No.: 1	00103	/ Title: F	PHASIC Hybrid, Scree	ning	g Specificatio	on for	/ Sec	ction 3.	1, wh	hich s	state	es:	
Subgroup 1, 100 percent electrical test of die. Each die shall be electrically tested, which may be done at the wafer level provided all failures are identified and removed from the lot when the die are separated from the wafer. When wafer/die level testing requirements are not specified in the procurement documents, the manufacturer/die supplier will choose the parameters, conditions and limits to assure compliance with the electrical characteristics.														
AFF	ECTED (O	Check all	that apply):								_	_		
FLIG	HT SYSTE	EMS:	_			GROUND SYST	'EMS:		<b></b>					
	Avionics			Electrical and Cables										
	Experime			Software/Firmware										
	Structures			Other:					Ot	her:				
REQUIRED APPROVAL DATE: 3/1/03														
REQUIRED JUSTIFICATION:														
												(Pa	ge 1 of 2)	

## STEREO CONFIGURATION CHANGE REQUEST

	TITLE:		CLASS:			NUMBER:				
For Office					Ι					
Use Only					II	DATE:				
CONTRACT/AGREEMENT NUMBER EFFECTIVITY:										
STEREO	NAS5-97271 🗸	IMPACT S-13635Y	PLASTIC NAS5-00132			SECC	HI S-13631Y			
DOCUMENTS/DRAWINGS TO BE REVISED:										
Document/E	Drawing Number:	Document/Drawing Title:	Section(s) No.			EO No.:	Date Completed:			
PROCESSING APPROVAL:										
C	СВ									
0	ut of Board									
E	mergency	Systems Engineer				Date				
CCB APPRO	VAL:									
CCB ACTION	DATE:	CCB ACTION ITEMS/CONDITIONS:								
A	pproved									
D	enied									
W	/ithdrawn									
Н	lold									
CLOSEOUT C	OMMENTS:		DATE OF				CLOSEOUT:			
			СМО							

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